

IN THE SPECIFICATION

Please replace the paragraph beginning at page 10, line 23, with:

FIG. 6 is a cross-sectional view of an example packaged integrated circuit 600 incorporating an integrated circuit die such as that shown in FIG. 4. The packaged integrated circuit 600 includes an integrated circuit die 602, which is coupled to a leadframe 604. The coupling between the leadframe and the die may be, for example, via one or more wire bonds, adhesive or thermal bonding, or other coupling mechanisms. The integrated circuit die 602 and leadframe 604 are at least partially encapsulated or otherwise enclosed by a packaging material 605. The leadframe, packaging material and manner in which the die is packaged may be entirely conventional, and are therefore not further described herein. Also, certain elements have been omitted from the figure for clarity and simplicity of illustration. Such omitted elements may include, by way of example, solder bumps, wire bonds, etc.